

Tuesday, April 15

■ IAAC Special Session

3D Chiplet Technologies for Automotive/AI Applications

Room A	
13:00	<p>Greeting Beth Keser, Zero ASIC, IMAPS Past President / US Chairs: Taiji Sakai, TSMC Japan 3DIC R&D Center, Beth Keser, Zero ASIC</p>
13:10	<p>Japan's strategy for Semiconductors Hisashi Kanazashi, Ministry of Economy, Trade and Industry / Japan Chairs: Taiji Sakai, TSMC Japan 3DIC R&D Center, Beth Keser, Zero ASIC</p>
13:30	<p>Latest Status of on-Substrate Material Development for CoWoS Packaging Shimpei Yamaguchi, TSMC Japan 3DIC R&D Center / Japan Chairs: Beth Keser, Zero ASIC, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>
14:00	<p>Advanced Packaging Technologies in Memory Applications for AI Era Ki Ill Moon, SK hynix /Korea Chairs: Beth Keser, Zero ASIC, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>
14:30	<p>Enabling Power Efficient AI with Advanced Packaging Hajime Saiki, AMD / US Chairs: Beth Keser, Zero ASIC, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>
15:00	<p>Chiplets and Advanced Packaging for AI Applications: Costs and Risks Amy Lujan, SavanSys Solutions / US Chairs: Beth Keser, Zero ASIC, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>
15:30	<p>Break</p>
15:45	<p>Developments in Advanced SoC Research for Automotive Nobuaki Kawahara, ASRA / Japan Chairs: Osamu Suzuki, Rapidus US, Yasuhiro Morikawa, ULVAC</p>
16:15	<p>Chiplets and Advanced Packaging for Automotive: Motivation and Opportunities Vikas Gupta, ASE / US Chairs: Osamu Suzuki, Rapidus US, Yasuhiro Morikawa, ULVAC</p>
16:45	<p>Chiplets in Automotive Electronics : Opportunities and Challenges Andreas Grassmann, Infineon Technologies / Germany Chairs: Osamu Suzuki, Rapidus US, Yasuhiro Morikawa, ULVAC</p>

	Room A	Room B	Room C	Room D	Room E
9:30	<p>WA1: iNEMI Session</p> <p>Chairs: Yoshihiro Tomita, Intel, Fumihiro Inoue, YOKOHAMA National University</p> <p>WA1-1 <Session Invited> A Study of Applying AI in Electronic Manufacturing</p> <p>Feng Xue¹, Masahiro Tsuruya², ¹IBM / Singapore, ²iNEMI / Japan</p> <p>WA1-2 The Study of Glass Core Substrates Warpage</p> <p>Kang Eu Ong¹, Junko Konishi², Yoichiro Sato², Tatsuro Yoshida³, Kei Murayama⁴, Makoto Tsukahara⁵, Haley Fu⁶, Intel Technology / Malaysia, ⁷AGC, ⁸Shinko Electric Industries / Japan, ⁹iNEMI / China</p> <p>WA1-3 Thermomechanical FEM Analysis of Sn-Bi Solder Joint During Temperature Cycling For Fine Pitch 1st Level Interconnect</p> <p>Toyohiro Aoki¹, Yasuharu Yamada², Sayuri Kohara³, Gokhale Shripad⁴, Sze Pei Lim⁵, Russell Kastberg⁶, Masahiro Tsuruya⁷, IBM Research / Japan, Intel / US, Indium / Malaysia, IBM / US, iNEMI / Japan</p> <p>WA1-4 Effect of Interfacial Wetting on First Level Interconnect Joint Formation For Low Temperature Solders-iNEMI Project</p> <p>Shripad Gokhale¹, Edwin Cetegen², Rui Zhang³, Sze Pei Lim⁴, Russell Kastberg⁵, Toyohiro Aoki⁶, Masahiro Tsuruya⁷, Intel / US, Indium / Malaysia, IBM Infrastructure / US, IBM Research, iNEMI / Japan</p>	<p>WB1: Cu Interconnection</p> <p>Chairs: Shoji Uegaki, Crane Research, Eiji Higurashi, Tohoku University</p> <p>WB1-1 Influence of Geometrical Design Based on Copper Direct Bonding Process</p> <p>Koharu Yuzawa¹, Hideki Kitada², Shima Shima Production, ³K.R.C.Group / Japan</p> <p>WB1-2 Reducing Electrical Resistivity of Copper-CNT Composite Film for High-Ampacity Back End of Line and Interconnection</p> <p>Y. Takeishi, K. Yasuda, The University of Osaka / Japan</p> <p>WB1-3 Elemental Characterization for Electroless Cu Interface Layer of Stacked Micro-via in Substrate by STEM and ToF-SIMS</p> <p>Masahiko Nishijima¹, Ming-Chun Hsieh¹, Zhang Zheng², Aiji Suetake³, Rieko Okumura⁴, Hiroyoshi Yoshida⁵, Chuantong Chen⁶, Hiroki Seto⁷, Yuhei Kitahara⁸, Kei Hashizume⁹, Kimihiro Yamanaka¹⁰, Katsuki Suganuma¹¹, The University of Osaka, ¹²Okuno Chemical Industries / Japan</p> <p>WB1-4 Thermo-Mechanical Reliability of Ag and Cu Joint Structure with EMC Molding</p> <p>YehRi Kim^{1,2}, Dongjin Kim¹, Korea Institute of Industrial Technology (KITECH), Korea University / Korea</p>	<p>WC1: Advanced Packaging-1</p> <p>Chairs: Noriyuki Fujimori, OLYMPUS, Koichi Hasegawa, JSR</p> <p>WC1-1 <Session Invited> Hybrid Bonding for Heterogenous Integration</p> <p>Viorel Dragoi¹, Hiroshi Yamamoto², ¹EV Group / Austria, ²EV Group / Japan</p> <p>WC1-2 <Session Invited> Advanced Packaging Activity at Arizona State University</p> <p>Hongbin Yu, Arizona State University / US</p> <p>WC1-3 Development of Fine-Pitch Cu-Cu Hybrid Bonding on Face-to-Back Structure for Three-Layer WoWoW: Impact of Wafer Warpage on Wafer Bonding Properties</p> <p>Yukako Ikegami, Kengo Kotoo, Kan Shimizu, Yoshihisa Kagawa, Hayato Iwamoto, Sony Semiconductor Solutions / Japan</p> <p>WC1-4 Low-Temperature Cu/Cu Hydrophilic Bonding Using Ar Ion Beam Activation</p> <p>Junsha Wang^{1,2,4}, Kai Takeuchi¹, Michitaka Kubota^{1,2}, Masaya Kawano^{1,2}, Takeshi Takagi^{1,2}, Masaki Niwa^{1,2}, Tadahiro Kuroda^{1,2}, Tadatomu Suga^{1,2,4}, The University of Tokyo, ³Research Association for Advanced Systems, ⁴Tohoku University, ⁵Meisei University / Japan</p>	<p>WD1: Emerging Technologies</p> <p>Chairs: Tadao Matsunaga, Tottori University, Kai Takeuchi, Tohoku University</p> <p>WD1-1 Packaging Design and Manufacturing of an Implantable Episclera Surface Stimulator</p> <p>Mian TAO¹, Chi-Chuen Jeffery LO¹, Chi-Ying TSUI¹, Senior Member, IEEE, Shi-Wei Ricky LEE^{1,2}, ¹The Hong Kong University of Science and Technology / Hong Kong, ²Hong Kong University of Science and Technology (Guangzhou) / China</p> <p>WD1-2 3D Miniaturization of Magnetic-Assisted Capsule Endoscope Using Mass-Transfer Cu Pillar Pin Assembly and Vacuum Printing Encapsulation</p> <p>Li-Cheng Shen¹, Sing Wu², Ming-Hung Chang¹, Chao-Hsuan Wang³, Tai-Lin Wu⁴, Hume-Yi Tsai¹, Chung-Ping Chang⁵, Kuan-Ying Shen¹, Hawk Yeh¹, ¹Universal Global Scientific Industrial (USI), ²Insight Medical Solutions (IMS) / Taiwan</p> <p>WD1-3 Multi-Layered Indoor Spatial Coordinate Definition Method and Compact Detection Module Using Fifth-Generation Mobile Communication System and Sensors</p> <p>Maho Terashima, Nobuaki Hashimoto, Suwa University / Japan</p>	<p>WE1: DMR-E-1</p> <p>Chairs: Ying Ying Lim, AIST, Masahiro Aoyagi, Kumamoto University</p> <p>WE1-1 Power Integrity Improvement for CoWoS-L[®] Using Simulation-Based Modeling of Deep Trench Capacitor 1100 fF/mm²</p> <p>Tzu-Yu Huang, Michael Yu, Jhen-Hong Lin, Mochtar Chandra, Christine Bair, L.C. Hung, James Chen, Taiwan Semiconductor Manufacturing / Taiwan</p> <p>WE1-2 Study of New Preconditioning for Solderability Testing</p> <p>Takaaki Sensui, Hideyuki Nagai, TDK / Japan</p> <p>WE1-3 A Machine Learning Model for Vickers Hardness of Sn-In-X Low-Temperature Solder</p> <p>Hao-Wei Kuo, Yu-chen Liu, National Chen Kung University / Taiwan</p> <p>WE1-4 Improved Electrical Reliability Within EMI/Shielding Case for the Assembly of Advanced Miniaturized Electronic Packages</p> <p>Masashi Nakahama¹, Akihiro Kiyosue¹, Mutsuharu Tsunoda¹, Morgana Ribas², MacDermid Performance Solutions Japan / Japan, ³MacDermid Alpha Electronics Solutions India / India</p>
11:10	Break				
11:10 11:20	<p>WA2: IMPACT Session</p> <p>Chairs: Jun Mizuno, National Cheng Kung University, Y. Liu, National Cheng Kung University</p> <p>WA2-1 <Session Invited> Alloying Effect on High Reliability Solder Materials</p> <p>Albert T. Wu, National Central University / Taiwan</p> <p>WA2-2 <Session Invited> Evaluation of Energy Dissipation Associated to Interface Debonding in Redistribution Interconnect</p> <p>Shih-Chen Lin, Ching-Jeng Ho, Tz-Cheng Chiu, National Cheng Kung University / Taiwan</p> <p>WA2-3 <Session Invited> Investigating the Electromigration Behavior within Copper Redistribution Line Using Numerical Simulation Methods</p> <p>Tai-Yu Pan¹, Min-Yan Tsai¹, Wen-Dung Hsu^{1,2}, ¹National Cheng Kung University, ²National Cheng Kung University, ASE Group / Taiwan</p>	<p>WB2: Cu-Cu Bonding</p> <p>Chairs: Junsha Wang, Meisei University, Kiyokazu Yasuda, The University of Osaka</p> <p>WB2-1 Investigation of Bonding Between Nanotwinned Cu and Nanocrystalline Cu</p> <p>Po-Hung Lai, Chih Chen, National Yang Ming Chiao Tung University / Taiwan</p> <p>WB2-2 Optimizing Cu-Cu Bonding Strength in Nanotwinned Cu Films Through Plasma-Induced Surface Roughening</p> <p>Ming-Chieh Chen, Chih Chen, National Yang Ming Chiao Tung University / Taiwan</p> <p>WB2-3 Light Exposure Pre-Treatment for Copper-to-Copper Direct Bonding</p> <p>Yu-Cheng Ke, Yao-Wen Zhang, Jenn-Ming Song, National Chung Hsing University / Taiwan</p>	<p>WC2: Advanced Packaging-2</p> <p>Chairs: Fumihiro Inoue, YOKOHAMA National University, Shoji Uegaki, Crane Research</p> <p>WC2-1 Regulating Sn Grain Orientations in Soldered Joints through CoSn₃</p> <p>Xinjie Wang, Hiroaki Tatsumi, Hiroshi Nishikawa, The University of Osaka / Japan</p> <p>WC2-2 Glass to Glass Joint by Low Temperature Soldering Using Localized Induction Heating Process</p> <p>Chi Hsuan Lin¹, Hiroaki Tatsumi¹, Jenn Ming Song², Hiroshi Nishikawa³, The University of Osaka / Japan, ⁴National Chung Hsing University / Taiwan</p> <p>WC2-3 Effect of Bi on Properties of Sn-9Zn Alloy for Interconnections</p> <p>Hao-Zhe Kao, Chih-Ming Liang, Yu-An Shen, Feng Chia University / Taiwan</p> <p>WC2-4 Design High Shear Strength Sn-Bi-X Lowtemperature Solders on Cu Substrate Using a Machine Learning Approach</p> <p>Pei-Zhen Wu, Yu-chen Liu, National Cheng Kung University / Taiwan</p>	<p>WD2: Polymer Materials</p> <p>Chairs: Koichi Hirano, Panasonic Holdings, Koichi Hasegawa, JSR</p> <p>WD2-1 <Session Invited> A Liquid Encapsulant with Excellent Weather Resistance, Long-term Reliability and Casting Properties</p> <p>Takayuki Kajihara, Toshio Suetsugu, Tatsuya IKeda, Satoshi Osawa, Nihon Gosei Kako / Japan</p> <p>WD2-2 Effect of Silica fillers on the Curing Reaction of Epoxy-Imidazole Thermoset Resin</p> <p>K. Naka¹, Y. Furushima¹, T. Hirano¹, Y. Taguchi¹, H. Torigoe², T. Takao³, A. Takase³, T. Nousou⁴, Y. Ishikawa⁵, K. Ishii⁶, ¹Toray Research Center, ²Sanyu Rec / Japan</p> <p>WD2-3 Electrical Conductivity Variations of Stretchable Printed Wires Examined from Hierarchic Deformation Behavior</p> <p>Masahiro Inoue, Rintaro Yamamoto, Gunma University / Japan</p> <p>WD2-4 Acceleration of Silver Micro-flake Sintering to Enhance Interconnection Integrity Using a Flexible Epoxy-based Binder</p> <p>Takanori Fukushima, Masahiro Inoue, Gunma University / Japan</p>	<p>WE2: DMR-E-2</p> <p>Chairs: Takayuki Ohba, Institute of Science Tokyo, Masahiro Aoyagi, Kumamoto University</p> <p>WE2-1 Riffined Measurement of the Specific Contact Resistivity and Reliability at the Interface Between Bismuth Telluride and Metals</p> <p>A. Katsura¹, M. Tsurumoto¹, Y. Hirose¹, D. Micucci², T. Sugahara³, ¹Kyoto Institute of Technology / Japan, ²Politecnico di Torino / Italy</p> <p>WE2-2 HV-H3TRB Evaluation of Ag and Cu Sintering Paste for Double-Sided Sintered Power Devices</p> <p>Felix Steiner¹, Dai Ishikawa², Hideo Nakako², Thomas Blank³, ¹Karlsruhe Institute of Technology / Germany, ²Resonac / Japan</p> <p>WE2-3 A Mesh Size Searching Method in WLP Reliability Prediction with Fixed Coffin-Manson Parameters</p> <p>Y. T. Su, K. N. Chiang, National Tsing Hua University / Taiwan</p> <p>WE2-4 Prototype of Device for Low-Temperature Cooking Using Dielectric Heating</p> <p>Kei Imai, Yuuki Furuyama, Kouji Kuramochi, Takahiko Yamamoto, Tokyo University of Science / Japan</p>
13:00	Lunch				
13:50	Award Ceremony				
13:50 14:30	Break				
14:30 14:40	Keynote Lecture I: Brightening the Future with Advanced Semiconductor Packaging Technologies				
14:40	<p>Yasushi Araki, SHINKO ELECTRIC INDUSTRIES</p> <p>Chairs: Taiji Sakai, TSMC Japan 3DIC R&D Center, Yasuhiro Morikawa, ULVAC</p>				
15:40 16:40	Break / Poster Session				
16:40	Keynote Lecture II: Digital Twins in Data Center Cooling: Meeting AI Demands With Smart Design and Innovation				
17:40	<p>Ali Heydari, NVIDIA</p> <p>Chairs: Risa Miyazawa, IBM Japan, Kai Takeuchi, Tohoku University</p>				
17:40 17:45	Introduction to ICEP 2026				
18:30 20:30	Welcome Reception				

Thursday, April 17

	Room A	Room B	Room C	Room D	Room E
8:30	Keynote Lecture III: Beyond Moore's Law: Semiconductor Packaging in the Chiplet Revolution Yasumitsu Oriti, Rapidus				
9:30	Chairs: Yasuhiro Morikawa, ULVAC, Fumihiro Inoue, YOKOHAMA National University				
9:40	Break				
9:40	<p>TA1: ADMETA/DPS Session</p> <p>Chairs: Yasuhiro Morikawa, ULVAC, Seichiro Higashi, Hiroshima University</p> <p>TA1-1 <Session Invited> Deposition of Dielectric Films from Plasma-Generated Aerosols Zachary Holman^{1,2}, ¹Arizona State University, ²Swift Coat / US</p> <p>TA1-2 <Session Invited> Advanced Plasma Etching Technology for Cutting-Edge Devices Michikazu Morimoto, Hitachi High-Tech / Japan</p> <p>TA1-3 <Session Invited> Multilayer Graphene Synthesis by Microwave Plasma CVD for Interconnect Application Takashi Matsumoto, Tokyo Electron Technology Solutions / Japan</p> <p>TA1-4 <Session Invited> Cultural Fusion ? Tadashi Fukuda, TECH EXTENSION / Japan</p>	<p>TB1: Advanced Metallic Materials</p> <p>Chairs: Go Hamasaka, Tokuyama, Tomoyuki Abe, Samsung Japan</p> <p>TB1-1 Development of Industrial Purification Methods for Silver Nanowires Used as Transparent Conductive Materials K. Sato^{1,2}, S. Kumon¹, J. Balachandran², Y. Sutou¹, ¹DOWA HOLDINGS, ²Tohoku University / Japan</p> <p>TB1-2 Phase Equilibria of the Fe-Sn-Zn Ternary System at 270°C Ssu-Chi Huang, Hsing-Tieh Lee, Yu-Pin Hsieh, Yee-Wen Yen, National Taiwan University of Science and Technology / Taiwan</p> <p>TB1-3 Copper Nano/Fine Particles as Joining Materials for Low Temperature Sintering Tetsu Yonezawa, Hokkaido University / Japan</p> <p>TB1-4 Cost-Effective and Low-Temperature Sintering of Oxidized Copper Nanoparticles for Power Electronics Tetsu Yonezawa, Hokkaido University / Japan</p>	<p>TC1: SMTA/Pan Pacific Session</p> <p>Chairs: Koichi Hasegawa, JSR, Charles E. Bauer, TechLead</p> <p>TC1-1 <Session Invited> A Novel Expansion Process for FO-WLP Using Tape Expansion, Self-Assembly, and Tape Frozen Detachment Technique Shinya Takyu, LINTEC / Japan</p> <p>TC1-2 <Session Invited> Conductive Cu Paste as a Via Filling Material for Through Glass Via (TGV) Yoshinori Ejiri, Resonac / Japan</p> <p>TC1-3 <Session Invited> Chip-to-Wafer Polymer Hybrid Bonding for Low-Temperature Process Takenori Fujiwara, Toray Industries / Japan</p>	<p>TD1: Solder Interconnect</p> <p>Chairs: Hiroshi Nishikawa, The University of Osaka, Junsha Wang, Meisei University</p> <p>TD1-1 High-Speed Solder Ball Shear Test and Component Shear Test for Evaluating the Robustness of Solder Joints Under Different Reflow Profiles Y. Y. Chen, Y. S. Zou, Vance Liu, M. H. Chung, C. L. Gan, Micron Technology / Taiwan</p> <p>TD1-2 Multiscale micromechanical Study of Polymer Core Solder Ball for BGA Interconnections Reliability S. Sao Joao¹, I. Malkorra¹, U. Costa², D. Chalavoux², S. Bucher³, N. Perardel⁴, G. Kermouche⁵, ¹University of Lyon, ²HALES Avionics SAS, ³HEF Group, ⁴Nicomac SA / France</p> <p>TD1-3 Enhanced Self-Propagating Exothermic Reaction Bonding with Nanostructured Cu/ Sn Interlayer Han Jiang^{1,2}, Changqing Liu², Jingyu Chen³, Yaohua Xu⁴, ¹Anhui University / China, ²Loughborough University, ³The University of Sheffield / UK</p> <p>TD1-4 Enhanced Electrochemical Migration Resistance of Fine-Pitch Ag Interconnects by Self-Assembly Monolayers Fan-Yi Ouyang, Hung-Lin Chen, Chien-Cheng Chiang, National Tsing Hua University / Taiwan</p>	<p>TE1: Optoelectronics-1</p> <p>Chairs: Koichi Takemura, AIO Core, Rai Kou-Takahashi, AIST</p> <p>TE1-1 <Session Invited> All-Photonics-Function Embedded Package Substrate Using 2.3D RDL Interposer for Co-Packaged Optics Akhiro Noriki¹, Hirota Uemura², Haruhiko Kuwatsuka¹, Naoki Matsui², Reona Motoji², Dan Maeda², Tomoya Sugita², Fumi Nakamura¹, Satoshi Suda¹, Takayuki Kurosu¹, Takeru Amano¹, AIST, ²Kyocera / Japan</p> <p>TE1-2 A Simulation Study for Optimal Conditions of Singlemode Polymer Optical Waveguides in Chip-to-Chip Connections Hiroki Ito, Yuji Furuta, Kenji Yanagisawa, Masaharu Kato, Hisashi Kaneda, Tomoharu Fujii, Shinko Electric Industries / Japan</p> <p>TE1-3 Refractive Index Profile Analysis of Single Mode Polymer Optical Waveguide by Using Propagation-Mode Near Field Method Masaki Matsumoto, Tomoharu Fujii, Kazuhiro Yoshida, Shinko Electric Industries / Japan</p>
11:20	Break				
11:30	<p>TA2: Glass PKG-1</p> <p>Chairs: Yoichiro Sato, AGC, Tetsuya Onishi, Grand Joint Technology</p> <p>TA2-1 <Session Invited> Glass Packaging Markets and Critical Issues to Solve Ejan Vardaman, TechSearch International / US</p> <p>TA2-2 High volume manufacturing of Through Glass Via (TGV) Wet etch for Glass Core Substrates for High Density 3D Advanced Packaging Applications Venugopal Govindarajulu¹, Coby Tao¹, Vengal Jagalam¹, Keshav Chandran¹, Katsumi Yoneda², Zia Karim¹, ¹Yield Engineering Systems / USA, ²Yield Engineering Systems / Japan</p> <p>TA2-3 Driving Efficiency in Advanced Packaging: TGV Tool Concepts and Supply Chain Impacts Richard Noack, Daniel Dunker, Roman Ostholt, Rafael Santos, Nils Anspach, LPKF Laser & Electronics / Germany</p> <p>TA2-4 Pre-Treatment for Adhesion Layer in Panel-Level Sputtering Applying an Improved Linear Ion Source A. Higashi, A. Ihori, T. Yuze, T. Terasawa, M. Wakai, Y. Morikawa, ULVAC / Japan</p>	<p>TB2: Low Temperature Solder Materials</p> <p>Chairs: Masahiro Inoue, Gunma University, Kiyokazu Yasuda, The University of Osaka</p> <p>TB2-1 Nanoindentation Study of Phases in Near-Eutectic Sn-Bi Alloy Xin Fu Tan¹, Viola Paul², Takahito Ohmura², Stuart D. McDonald¹, Kazuhiro Nogita¹, ¹The University of Queensland / Australia, ²National Institute for Materials Science (NIMS) / Japan</p> <p>TB2-2 Tensile Properties of Sn-37wt%Bi and Sn-57wt%Bi at Temperatures Below 0°C Xiaozhou Ye, Stuart D McDonald, Xin Fu Tan, Kazuhiro Nogita, The University of Queensland / Australia</p> <p>TB2-3 Planar Geometry Solder Joint Study of Alloying Effects on Sn-Bi Electromigration Impacts Prabjit Singh¹, L. Palmer¹, T. Wassick¹, R. F. Aspandiar², B. Franco³, L.A. Swaminathan⁴, H. Fu⁵, V. Vasudevan⁶, A. Allen⁷, K. Howell⁸, K. Murayama⁹, H. Zhang¹⁰, A. Lifton¹¹, T. Munson¹⁰, S. Middleton¹⁰, M. Sarangapani¹¹, ¹IBM, ²Intel / US, ³iNEM / China, ⁴Dell Technologies, ⁵HP / US, ⁶Nihon Superior, ⁷Shinko Electric Industries / Japan, ⁸Indium, ⁹MacDermid Alpha Electronics Solutions, ¹⁰Foresite / US, ¹¹Heraeus Materials Singapore / Singapore</p> <p>TB2-4 Mechanical Tensile Behaviors of Sn-Bi Lead-Free Solder Alloys Under Different Strain Rates and Temperatures Min-Cheng Yu, Nien-Chun Lin, Hsin-Chih Shih, Ching-I Tsai, Chin-Li Kao, Chen-Chao Wang, C.P. Hung, Wen-Fung Pan, Advanced Semiconductor Engineering (ASE) / Taiwan</p>	<p>TC2: ISMP Session</p> <p>Chairs: Kai Takeuchi, Tohoku University, Go Hamasaka, Tokuyama</p> <p>TC2-1 <Session Invited> 2.xD Advanced Packaging with Bridge Die Platforms: Development, Structure, and Reliability Jae-Sung Lim, Sangkyu Jang, Jin-Wook Jang, Yong-Nam Koh, Jayden Donghyun Kim, HANA Micron / Korea</p> <p>TC2-2 <Session Invited> The Study on Ultra-Precision Surface Measurement Technologies in the Hybrid Bonding Process Joonho You, nexensor / Korea</p> <p>TC2-3 <Session Invited> Nanomechanical Modeling of Fracture and Plasticity in Metallic Multilayers During Thermal Cycles Ill You, Seoul National University / Korea</p> <p>TC2-4 <Session Invited> Single-Additive Cu Electrodeposition for Defect-Free TSV Filling MyungJunKim, Sungkyunkwan University / Korea</p>	<p>TD2: Power Electronics-1</p> <p>Chairs: Toyohiro Aoki, IBM Japan, Tomoyuki Hatakeyama, Toyama Prefectural University</p> <p>TD2-1 Power Variation Analysis During Transient Thermal Measurement of Semiconductor Packages Shuhei FUKUNAGA¹, Tomoaki HARA², Tsuyoshi FUNAKI¹, ¹The University of Osaka, ²Siemens / Japan</p> <p>TD2-2 Large-Area Bonding for Direct Cooling for Applications in Power Inverters Shin-Il Kim¹, Yong-Ho Ko^{1,2}, Dongjin Kim¹, ¹Korea Institute of Industrial Technology (KITECH), ²University of Science Technology (UST) / Korea</p> <p>TD2-3 Numerical and Experimental Investigations on Thermo-Stable Reliability of a Physical Property-controlled Type High-Heat Dissipation Spacer for Double-Side Cooling Power Modules Dongjin Kim¹, ByeongChan Kim¹, YehRi Kim¹, KUE JIN HAN², TAESEONG HAN², ¹Korea Institute of Industrial Technology (KITECH), ²KOSTECSSYS / Korea</p> <p>TD2-4 Thermal Stability of Vertical Type Shunt Resistors for Use in Double Side Cooling SiC Power Modules Dongjin Kim¹, YehRi Kim¹, ByeongChan Kim¹, KUE JIN HAN², TAESEONG HAN², ¹Korea Institute of Industrial Technology (KITECH), ²KOSTECSSYS / Korea</p>	<p>TE2: Optoelectronics-2</p> <p>Chairs: Atsushi Sugitatsu, OITDA, Takeru Amano, AIST</p> <p>TE2-1 Reflowable Ceramics Multifiber Ferrule for Co-Packaged Optics Alexander William Setiawan Putra, Kentaro Matsuda, Motohito Takezaki, Hakusan / Japan</p> <p>TE2-2 Novel Passive Alignment Implementation Using 41°-Cleaved Fiber Array for Silicon Photonic Micro-Transceiver Michiyo Kubo, Shigeru Kobayashi, Koichi Takemura, Makoto Kuwata, Kazuhiko Kurata, AIO Core / Japan</p> <p>TE2-3 <Session Invited> Fabrication and Transient Optical Response of 910nm Broadband Near-IR Remote Phosphor-converted LED Atsushi Okuno¹, Jang Uk An², ¹Green Planets / Japan, ²ALLIX / Korea</p>
13:10	Lunch Time				
13:10					
14:00					

Contact Information

Please contact for any inquiries about:

Registration

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Conference Programs

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https://www.jiep.or.jp/icep/

	Room A	Room B	Room C	Room D	Room E
14:00	<p>TA3: Glass PKG-2 Chairs: Yoichiro Sato, AGC, Tetsuya Onishi, Grand Joint Technology TA3-1 <Session Invited> High AR TGV Direct Wet Cu Metallization on Glass A. Okimoto¹, T. Onishi^{1,2}, K. Inoue¹, M. Takayama¹, ¹Koto Electric / Japan, ²Grand Joint Technology / Hong Kong TA3-2 Development of Acid Copper Plating Chemicals for Advanced Packaging with TSV and TGV Nobuaki Nagano, Shota Suzuki, Ryo Aizawa, Yusuke Suga, Tetsuro Eda, JCU / Japan TA3-3 <Session Invited> Acid Copper Plating Process for RDL Suitable for Glass Substrate Atsuya Yamaguchi, Kohei Imahase, Reito Kobayashi, Tetsuro Eda, JCU / Japan TA3-4 <Session Invited> Integrated Low Temperature Based Glass Core Substrate Manufacturing Solutions Minimizing SeWaRe Type failures Christian Buchner, SCHMID Group / Germany</p>	<p>TB3: Materials for Hybrid Bonding Chairs: Masahisa Fujino, Institute of Microelectronics, A*STAR, Fumihiro Inoue, YOKOHAMA National University TB3-1 Enhancement of Bonding Strength Between Cured Polymer Dielectrics and SiO₂ by Plasma Activation Treatment Natsumi Sumito, Wataru Okada, Ryo Hayakawa, Satoshi Otsuka, Yuzo Nakamura, Yutaka Hisamune, Satoshi Inada, Mitsui Chemicals / Japan TB3-2 Hybrid Bonding of Cu and Manganin by Using IPA-VUV Irradiation Fu-Ling Chang^{1,2}, C. Robert Kao¹, Akitsu Shigetou¹, ¹National Taiwan University / Taiwan, ²National Institute for Materials Science / Japan TB3-3 Surface Modification of Cu Native Oxide: Ag Displacement for Homogeneous Layering Shubhayan Mukherjee¹, Akitsu Shigetou¹, Shih-kang Lin¹, ¹National Cheng Kung University / Taiwan, ²National Institute for Materials Science / Japan TB3-4 Dimensional Effects on Grain Size and Surface Orientation of Nanocrystalline Cu in SiO₂ Micro-Vias Te-Hao Chao, Hwai-En Lin, Dinh-Phuc Tran, Chih Chen, National Yang Ming Chiao Tung University / Taiwan</p>	<p>TC3: Advanced Packaging-3 Chairs: Kiyokazu Yasuda, The University of Osaka, Masashi Nakazawa, Sony Semiconductor Solutions TC3-1 The Effect of Key Factors on 3D X-ray Imaging for Fan-Out Package Fan-Ju Hsiao, Yi-Sheng Lin, Cheng-Hsin Liu, Advanced Semiconductor Engineering / Taiwan TC3-2 Chemical Identification of Foreign Matters in a Cavity Using Submicron Infrared Spectroscopy Michael K. F. Lo¹, Naoki Baden², Hanae Kobayashi¹, Norio Urayama¹, ¹Photothermal Spectroscopy / US, ²Nihon Thermal Consulting / Japan TC3-3 In-situ EBSD Tensile Behaviors of Pressured Silver Sintered Structures Ha-Young Yu, Min-Su Kim, Dongjin Kim, Korea Institute of Industrial Technology (KITECH) / Korea TC3-4 Simulation and Experimental Analysis of Capillary Underfill in 2.5d Multi-Chip Modules Chien-Ting Wu¹, Kazuki Noguchi¹, Yu-En Liang¹, Wei-Yu Lin¹, Zi-Hsuan Wei¹, Ching-Kai Chou¹, Leo Shen¹, ¹CoreTech System (Moldex3D) / Taiwan, ²SANYU REC / Japan</p>	<p>TD3: Power Electronics-2 Chairs: Tomoyuki Hatakeyama, Toyama Prefectural University, Masahiro Aoyagi, Kumamoto University TD3-1 Effect of Ion Implantation on Suppression of Stacking Fault Expansion in 4H-SiC A. Myalitsin^{1,2}, V. Maeckel¹, T. Yoda¹, T. Ohba¹, ¹Institute of Science Tokyo, ²ANVOS Analytics / Japan TD3-2 Non-destructive X-ray Orientation Mapping of Die-attach Solder for Thermal Cycling Test Yujiro Hayashi¹, Jaemyung Kim¹, Makina Yabashi¹, Hiroaki Tatsumi¹, ¹RIKEN Spring-8 Center, ²The University of Osaka / Japan TD3-3 Power Cycle Testing, Behaviour of Clip-Sintered Bare Dies Felix Steiner¹, Janis Blank¹, Dai Ishikawa², Hideo Nakako², Liuda Mereacre¹, Thomas Blank¹, Karlsruhe Institute of Technology / Germany, ²Resonac / Japan TD3-4 Lower Inductance of POL Double Layer Facing Structure Power Module Takumi Yumoto¹, Takumi Ikeda¹, Yoichi Nishihara¹, Keita Suzuki¹, Yoshikazu Takahashi¹, Koji Bando¹, ¹Shinko Electric Industries, ²Tohoku University / Japan</p>	<p>TE3: DMR-M-1 Chairs: Risa Miyazawa, IBM Japan, Naotaka Tanaka, Resonac TE3-1 A Novel FOWLP Process Emulator for Predicting Time-Dependent Plastic Effects in Multi-Step Accumulated Thermal-Mechanical Asymmetric Warpage Shang-Feng Hsu, Kuo-Shen Chen, National Cheng-Kung University / Taiwan TE3-2 Warpage Control Strategy of Embedded Die Packaging on SESUB Technology Wei-Hong Lai, Chun-Yu Yen, Chung-Hung Lai, Tsung-Yuan Yang, Chin-Li Kao, Chen-Chao Wang, Advanced Semiconductor Engineering (ASE) / Taiwan TE3-3 Micro-Bump Connection and Chip Warpage Control Using the Reflow Process T. Igarashi, M. Togawa, M. Nakazawa, H. Iwamoto, Sony Semiconductor Solutions / Japan TE3-4 Warpage Behavior of Three-Phase SiC MOSFET Power Module During Fabrication Y. H. Liao¹, H. C. Cheng¹, Y. L. Liu¹, Y. C. Liu², K. S. Kao², T. C. Chang¹, ¹Feng Chia University, ²Industrial Technology Research Institute / Taiwan</p>
15:40 16:00	Break				
16:00	<p>TA4: Heterogeneous Integration Roadmap Chairs: Rozalia Beica, Rapidus Design Solutions, Yasumitsu Orii, Rapidus TA4-1 <Session Invited> IIoT enabled by Heterogeneous Integration and AI Wei-Chung Lo, Industrial Technology Research Institute (ITRI) / Taiwan TA4-2 <Session Invited> Scalable 3D Chiplet Integration for AI Inference Applications Farhang Yazdani, BroadPak / US TA4-3 <Session Invited> Revolutionizing the Future: The Growth of Heterogeneous Integration, Chiplets, and Advanced Packaging Rozalia Beica, Rapidus Design Solutions / US TA4-4 <Session Invited> Heterogeneous Integration Roadmap: Emerging Research Devices Meyya Meyyappan, Retired / US</p>	<p>TB4: Intermetallic Compound for Electronic Packaging Chairs: Go Hamasaka, Tokuyama, Akitsu Shigetou, National Institute for Materials Science TB4-1 Phase Transitions of the Cu₃Sn₂ phase Under Electric Currents Shubhayan Mukherjee, Yu-chen Liu, Shih-kang Lin, National Cheng Kung University / Taiwan TB4-2 Intermetallic Compound Formation and Growth Behavior Between Ruthenium and Tin System Hsiu-mei Yang¹, Tzu-hsuan Huang¹, Yu-hsuan Lin², Min-cian Chen², Shih-kang Lin¹, ¹National Cheng Kung University, ²Taiwan Semiconductor Manufacturing / Taiwan TB4-3 A Study on the Growth Kinetics and Mechanical Properties of IMCs in Au-In joints Chih-Chia Bill Chang, C. R. Kao, National Taiwan University / Taiwan TB4-4 In-Situ Observations of Crack Propagation and Microstructure Evolution in a SAC305/ Cu Solder Joint Using High-Voltage Electron Microscopy Kazuhiro Nogita¹, Xin F. Tan¹, Jiye Zhou¹, Stuart D. McDonald², Keith Sweatman², Flora Somidin², Hiroshi Maeno³, Kazuhiro Yasuda⁴, ¹The University of Queensland / Australia, ²Nihon Superior / Japan, ³University Malaysia Perlis (UniMAP) / Malaysia, ⁴Kyushu University / Japan</p>	<p>TC4: Advanced Packaging-4 Chairs: Yoshihiro Tomita, Intel, Noriyuki Fujimori, OLYMPUS TC4-1 Micro Ball Mount Total Process in Wafer-Level and Panel-Level in Chip Preparation for Next on Large Panel-Level Package Jia Sang Weng, Cong-Wei Chen, Shih Yu Wang, Ping-Feng Yang, Jen-Kuang Fang, Advanced Semiconductor Engineering / Taiwan TC4-2 Studies of the Twin Coherency on Electroless (111) Nanotwins Po-Shao Shih¹, I-En Chen¹, Chin-Li Kao², Yung-Sheng Lin², Yun-Ching Hung², C.R. Kao¹, ¹National Taiwan University, ²Advanced Semiconductor Engineering (ASE) Group / Taiwan TC4-3 Smoothing of Plated Au Bumps Based on Template-Stripping for Low-Temperature Bonding Shogo Koseki¹, Kai Takeuchi¹, Le Hac Huong Thu¹, Takashi Matsumae², Hideki Takagi², Yuichi Kurashima², Takahiro Tsuda², Tomoaki Tokuhisa², Toshikazu Shimizu², Eiji Higurashi¹, ¹Tohoku University, ²National Institute of Advanced Industrial Science and Technology (AIST), ³Kanto Chemical / Japan TC4-4 Superior Electrical Characteristics of Au-Sn Intermetallic Compound with Ultra-Thin Buffer Layer Structure in Eutectic Bonding Technology for 3D Integrated Circuits Applications Cheng-Yu Wei¹, Chiao-Yen Wang¹, Pei-Ru Lee¹, Mu-Ping Hsu¹, Yi-Chieh Tsai², Wun-Kai Wang², Kuan-Neng Chen¹, ¹National Yang Ming Chiao Tung University, ²TXC / Taiwan</p>	<p>TD4: Power Electronics-3 Chairs: Tomoyuki Hatakeyama, Toyama Prefectural University, Masahiro Aoyagi, Kumamoto University TD4-1 <Session Invited> Wire Bondless WBG Power Devices with Sinterconnect Technology Ali Roshanghias, Silicon Austria Labs GmbH / Austria TD4-2 Cost-Performance Silver- Aluminum Composite Sinter Paste with Improved Joint Reliability in SiC Power Device Applications Chuantong Chen^{1,2}, Fupeng Huo¹, Kazutaka Takeshita¹, Hiroaki Miyake¹, Katsunori Suganuma¹, ¹The University of Osaka, ²Yamato Scientific, ³Tokyo City University / Japan TD4-3 Investigates of Silver Sintered Process by Silver Thin Films and Nanotwinned Silver Thin Films Shin-Yi Huang¹, Yan-Cheng Liu¹, Ping-Chun Kao¹, Yung-Min Hsieh¹, Yu-Hua Wu¹, Fan-Yi Ouyang², Tao-Chih Chang¹, ¹Industrial Technology Research Institute, ²National Tsing Hua University / Taiwan</p>	<p>TE4: DMR-M-2 Chairs: Toyohiro Aoki, IBM Japan, Naotaka Tanaka, Resonac TE4-1 Silica Fillers Embedded in Epoxy Molding Compound Cause Inner Stress Concentration Ayumi Haginawa¹, Masaya Ukita¹, Keisuke Wakamoto¹, Yuya Shtishige², Keizo Arai², Ken Nakahara¹, ¹ROHM, ²Resinous Kasei / Japan TE4-2 Direct Observation of Copper Oxidation as a Cause of Delamination at the Interface of Copper and Epoxy Molding Compounds Keisuke Wakamoto, Masaya Ukita, Ayumi Haginawa, Ken Nakahara, ROHM / Japan TE4-3 Comparison of Thermomigration Velocity between Sn-Cu₃ and Ternary Sn-Bi-In Solder Yifan Yao¹, Xingchao Mao¹, Yuanxing Duan¹, Qinglei Sun², K. N. Tu¹, Yingxia Liu¹, ¹City University of Hong Kong, ²China University of Geosciences / China TE4-4 Predictive Validity for Sintered Die-Attach Performance based on Cross-Sectional Morphology Runhua Gao¹, Hiroaki Tatsumi¹, Takanori Kobatake², Minoru Ueshima², Hiroshi Nishikawa¹, ¹The University of Osaka, ²Daicel / Japan</p>
17:40 19:10	Poster Session & Sponsors Exhibition				

■Registration

Registration Information

Early-Bird Registration Due: March 27th, 2025
Pre-Registration Due: April 15th, 2025
On-site registration is available from April 15th, 2025.

Registration Fees

Fees are shown as “Early-Bird [On-Site]”. All registrations include complimentary conference proceedings and attendance to live sessions and receptions.

Members of JIEP/IEEE/iMAPS:	¥45,000 [¥52,000]
Members of Partner Organizations:	¥50,000 [¥57,000]
Non-Members:	¥60,000 [¥67,000]
Students:	¥20,000 [¥23,000]
Additional Welcome Reception Ticket:	¥10,000 / person

Partner Organizations: Japan Electronics and Information Technology Industries Association / Japan Electronics Packaging and Circuits Association / Japan Jisso Technology Transfer Association (to be confirmed) / Japan Society of Powder and Powder Metallurgy / Japan Welding Society / Optoelectronics Industry and Technology Development Association / Smart Processing Society for Materials, Environment & Energy / The Electrochemical Society of Japan / The Institute of Electrical Engineers of Japan / The Institute of Electronics, Information and Communication Engineers / The Japan Society for Precision Engineering / The Japan Society of Applied Physics / The Society of Chemical Engineers, Japan / The Surface Finishing Society of Japan

Friday, April 18

	Room A	Room B	Room C	Room D	Room E
8:30	<p align="center">Keynote IV: Recent Development Trend of FC-BGA Substrate With Chip-Let Structures Driven by HPC Applications Genjin Mago, Ajinomoto Fine-Techno</p> <p align="center">Chairs: Toyohiro Aoki, IBM Japan, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>				
9:15	<p align="center">Keynote V: Strategic Directions for Advanced Packaging Subramanian S. Iyer, University of California, Los Angeles</p> <p align="center">Chairs: Toyohiro Aoki, IBM Japan, Taiji Sakai, TSMC Japan 3DIC R&D Center</p>				
10:00	<p align="center">Break</p>				
10:00-10:10	<p align="center">Break</p>				
10:10	<p>FA1: Advanced Packaging and Thermal Chairs: Hitoshi Sakamoto, Huawei Technologies Japan, Tomoyuki Hatakeyama, Toyama Prefectural University FA1-1 <Session Invited> Innovations in Hybrid Bonding and Thermal Management for Advanced Packaging Kuan-Neng Chen, National Yang Ming Chiao Tung University / Taiwan FA1-2 <Session Invited> Multistacking bonding technologies, die-level co-integration and their technical challenges Masahisa Fujino, Institute of Microelectronics, A*STAR / Singapore FA1-3 <Session Invited> AI-Accelerated Multiscale Thermal & Mechanical Simulations for Advanced Packaging and IC Design Alexander J Gabouric, DeepSim / US FA1-4 <Session Invited> Micro- and Nano-Scale Thermal Property Measurements for Advanced Semiconductor Packages Using Frequency-Domain Thermoreflectance Microscopy Tomoya Uchiyama, ScienceEdge / Japan</p>	<p>FB1: Glass/Plating Process Chairs: Yoichiro Sato, AGC, Taiji Sakai, TSMC Japan 3DIC R&D Center FB1-1 <Session Invited> JPCA Technology Roadmap for Glass Substrates Henry H. Utsunomiya, Interconnection Technologies / Japan FB1-2 <Session Invited> Low CTE Copper Electrodeposit Kazuo Kondo, Anh Nahat, Fine Feature Electrodeposition Laboratory / Japan FB1-3 Laser Applications in Micro-machining of Glass Material Substrates Hsiang-Chen Hsu¹, Shih-Jeh Wu¹, Wen-Fei Lin², Shui-Cheng Huang³, Pei-Chieh Chin⁴, I-Shou University, ¹E&R Engineering / Taiwan FB1-4 Predicted Cu Plating Thickness Distribution in Fanout Panel Level Package with Global/Local Model Yi-Lun Hung, Yung-Sheng Lin, Min-Yan Tsai, Mingtzuang Kuo, Ling-yuan Chang, Chen-Chao Wang, Ping-Feng Yang, Chin-Pin Hung, Advanced Semiconductor Engineering (ASE) Group / Taiwan</p>	<p>FC1: Advanced Packaging-5 Chairs: Yoshihiro Tomita, Intel, Fumihiro Inoue, YOKOHAMA National University FC1-1 Elimination of Leakage in NaOH-activated Cu/SiO₂ Hybrid Bonding for Plasma-Free Surface Activation Scheme Huai-En Lin¹, Yu-Xiang Huang¹, Wei-Lan Chiu², Hsiang-Hung Chang³, Chih Chen⁴, ¹National Yang Ming Chiao Tung University (NYCU), ²Industrial Technology Research Institute (ITRI) / Taiwan FC1-2 Sub 100 nm Grain Size Electroplated Copper for Low Temperature Bonding Applications Jian-Yuan Huang¹, Dinh-Phuc Tran², Kang-Ping Lee³, Tsung-Chuan Chen⁴, Yao-Tsung Chen⁵, Emile Kuo⁶, Stream Chung⁷, Chih Chen⁸, ¹National Yang Ming Chiao Tung University, ²Chemleaders / Taiwan FC1-3 Sintered Cu-to-Cu Joints Using Cu Dendritic Structure Formed by a Dynamic Hydrogen Bubble Template with Cetyltrimethylammonium Bromide Ji-Hyun Kim, Hiroaki Tatsumi, Hiroshi Nishikawa, The University of Osaka / Japan FC1-4 Investigation of Cu-to-Cu Bonding Featuring Indium Passivation and a Tin Diffusion Barrier Layer Y. C. Tseng¹, Y. S. Lin¹, Y. C. Hung², C. R. Kao³, ¹National Taiwan University, ²Advanced Semiconductor Engineering (ASE) Group / Taiwan</p>	<p>FD1: 5G, Wiewless & Components Chairs: Norimasa Fukazawa, DIC, Keiju Yamada, Toshiba FD1-1 A 28-GHz 2x2 Antenna Array Integrated with a Butler-Matrix Beamformer IC Based on AiP Technology Wen-Chun Hsiao, Hong-Sheng Huang, Yu-Chang Hsieh, Chia-Ching Chu, Sheng-Chi Hsieh, Chen-Chao Wang, Advanced Semiconductor Engineering / Taiwan FD1-2 Analysis and Optimization of a Compact 1x4 Array Antenna for 5G Application Hong-Sheng Huang, Wen-Chun Hsiao, Yu-Chang Hsieh, Chia-Ching Chu, Sheng-Chi Hsieh, Chen-Chao Wang, Advanced Semiconductor Engineering / Taiwan FD1-3 Evaluation of Effective Permittivity of Multilayer Strip-Line Structure With Air Layers Under Substrate Deformation and Prototype of Deformation Suppression Structure USHIYAMA Taiyo¹, SASAKI Mai¹, TOMIOKA Sayu¹, HAZEMOTO Tsyoshi¹, ONO Satoshi¹, MASUI Sho¹, KOJIMA Takafumi¹, SAKAI Takeshi¹, ¹University of Electro-Communication, ²National Astronomical Observatory Japan / Japan FD1-4 Effects of Magnetic Field Exposure on Emotional Responses in Living Organisms Daiki Hirabayashi, Yuno Matsuyama, Daisuke Yamada, Akiyoshi Saitoh, Takahiko Yamamoto, Tokyo University of Science / Japan</p>	<p>FE1: DMR-M-3 Chairs: Risa Miyazawa, IBM Japan, Chuantong Chen, The University of Osaka FE1-1 High-Speed Ball Shear Mechanism on Ni-Au Substrate & Thermal Aging Effect Nien-Chun Lin, Hsin-Chih Shih, Ching-I Tsai, Chin-Li Kao, Chen-Chao Wang, C.P. Hung, Advanced Semiconductor Engineering (ASE) / Taiwan FE1-2 Study on the Global-Local Method with Critical Mesh Size Control for 3D Wafer-Level Packaging Simulation Time Reduction C. A. Yang, K. N. Chiang, ¹National Tsing Hua University / Taiwan FE1-3 Advanced Short Defect Repair Technique for Enhancing Yield in Packaging Architectures Adam Ginsburg, Oded Mor, Guy Levi, Guy Amrani, KLA / Israel FE1-4 Characterization of Signal Variations During the Self-Sharpening Process of Ceramic Diamond Grinding Wheels Yu-Kun Lin, Feng Chia University / Taiwan</p>
11:50	<p align="center">Lunch Time</p>				
11:50-12:40	<p align="center">Lunch Time</p>				
12:40	<p>FA2: Die Level Hybrid Bonding Technology Chairs: Fumihiro Inoue, YOKOHAMA National University, Marie Sano, Yokohama National University FA2-1 <Session Invited> Die to Wafer Hybrid Bonding: from Challenge to a New Industry Standard Pavel Scrogglazov, BESI / Netherlands FA2-2 <Session Invited> Wafer Bonding Advances & 3D Applications Hiroshi Yamamoto, EV Group / Japan FA2-3 <Session Invited> Suss Direct D2W Hybrid Bonding Solutions Thomas Schmidt, Philippe Muller, SUSS MicroTec Solutions / Germany</p>	<p>FB2: Interposer Chairs: Masashi Nakazawa, Sony Semiconductor Solutions, Tomoyuki Abe, Samsung Japan FB2-1 Multi-Stepped Solder Resist Patterning Technology for Advanced Packaging Meiten Koh¹, Raimu Kasuga¹, Yuji Toyoda², Taiyo Ink Mfg. ³Mitsubishi Paper Mills / Japan FB2-2 Moisture Diffusion Analysis of FOCos Package During Assembly Processes Dao-Long Chen, Tang-Yuan Chen, Fan-Yu Min, Wei-Hang Tai, Chen-Hung Lee, Chen-Chao Wang, Chih-Ping Hung, Advanced Semiconductor Engineering / Taiwan FB2-3 Anti-Oxidation for Copper by Galvanic Replacement Yu-hao Chou, Kun-yuan Zeng, Shih-kang Lin, National Cheng Kung University / Taiwan FB2-4 Adhesion Characteristics of Directly Sputtered Copper Seed Layer on Cycloolefin Polymer with Atmospheric Pressure Plasma Treatment A. Shimizu^{1,2}, S. Endo¹, ¹Ushio, ²Gifu University / Japan</p>	<p>FC2: Advanced Packaging-6 Chairs: Kiyokazu Yasuda, The University of Osaka, Akitsu Shigetou, National Institute for Materials Science FC2-1 Development of Warpage Control Techniques in Multi-Chip Fan-Out System-in-Package (SiP) Using Redistribution Layer Technology Jr-Wei Peng, Chih-Cheng Hsiao, Chin-Hung Wang, Industrial Technology Research Institute (ITRI) / Taiwan FC2-2 Advanced Packaging Solutions by Integrating 2.5D/3D Chiplet, Wafer Panel Level Package K. Izusawa, S. Teramoto, Y. Kajikawa, S. Hayashiguchi, T. Kubota, TOWA / Japan FC2-3 Cu Pillar Plating Process on Large Panel Fan-Out for High Performance Computing Application Powei Lu, Ming Tzung Kuo, Jeffrey Yang, Yuan Feng Chiang, Jen Kuang Fang, Advanced Semiconductor Engineering (ASE) / Taiwan FC2-4 A Novel UV Curable Wafer Back Side Protection Film Jun Maeda, Toshiaki Inoue, Soki Sato, Shigeyuki Yamashita, Shinya Takyu, LINTEC / Japan</p>	<p>FD2: Thermal Management-1 Chairs: Tomoyuki Hatakeyama, Toyama Prefectural University, Hitoshi Sakamoto, Huawei Technologies Japan FD2-1 <Session Invited> Thermal Resistance Cross Interfaces in Electronics Zhe Cheng, Peking University / China FD2-2 <Session Invited> Enhanced Performance of High-Power Density Semiconductor Chips Using CVD Diamond Heat Spreaders Ian Friel, Element Six / UK FD2-3 Optimization of Baking Temperature for Minimization of Interfacial Thermal Resistance in Polymer/SiC Bilayer Structure Using Optical-Interference Contactless Thermometry (OICT) Jiawen Yu, Hiroaki Hanafusa, Seichiro Higashi, Hiroshima University / Japan FD2-4 A fundamental Study on Interfacial Properties of Indium Thermal Interface Materials Po-hsiang Juan, Kuan-chen Kung, Shih-kang Lin, National Cheng Kung University / Taiwan</p>	<p>FE2: DMR-M-4 Chairs: Risa Miyazawa, IBM Japan, Tetsuya Onishi, Grand Joint Technology FE2-1 Simulation of CUF Fillet Height and Minimize Void on Reliability Tzu Chieh Chien, Yuan Hung Sun, Chao Lin Shih, Hui Ching Liu, Lu Ming Lai, Kuang Hsiung Chen, Advanced Semiconductor Engineering / Taiwan FE2-2 Sine and Random Vibration Analysis of SAC305 Electronic Assemblies Based on PCB Strain J-B. Libot, P. Milesi, Hooke Electronics / France FE2-3 Thermal Stress-Strain Behavior of Cu on Metallized Si₃N₄ Substrate Under Thermal Cycling Test by Digital Image Correlation Minh Chu Ngo, Hiroyuki Miyazaki, Kiyoshi Hirao, Tatsuki Ohji, Manabu Fukushima, National Institute of Advanced Industrial Science and Technology (AIST) / Japan FE2-4 Optimized Flux-less Bonding Process for High Throughput Using Simplified Equipment Takayuki Miyoshi¹, Kentaro Mihara¹, Takashi Hare, Katsumi Terada¹, Toyoharu Terada¹, Chienshuo Huang², Yuhao Lo³, Jun Mizuno², ¹Toray Engineering / Japan, ²National Cheng Kung University / Taiwan</p>
14:20	<p align="center">Break</p>				
14:20-14:30	<p align="center">Break</p>				
14:30	<p>FA3: Glass PKG-3 Chairs: Yoichiro Sato, AGC, Tetsuya Onishi, Grand Joint Technology FA3-1 Examination of Panel-Level Manufacturing Methods for Glass Core Substrates Shun Mitarai, Kiwamu Adachi, Takahiro Igarashi, Kosuke Seki, Naoki Kakoiyama, Yuto Tanaka, Shuichi Oka, Masashi Nakazawa, Hayato Iwamoto, Sony Semiconductor Solutions / Japan FA3-2 <Session Invited> Challenge for Glass Core Substrate with the Stress Analysis and Reliability Satoru Kuramochi, Dai Nippon Printing / Japan FA3-3 <Session Invited> Multilayer Glass substrate (G-ALCS) for Advancing Packaging Innovation Akira Tamura, FICT / Japan FA3-4 <Session Invited> Glass PKG Technology Trend & Core Items Tetsuya Onishi, Grand Joint Technology / Hong Kong</p>	<p>FB3: Printing Process Chairs: Eiji Higurashi, Tohoku University, Koichi Hirano, Panasonic Holdings FB3-1 Evaluation of Printing Characteristics of Inks Containing Plasmonic Nanoparticles Akinobu Yamaguchi¹, Toshiya Yasunaga², Kyoko Namura³, Motofumi Suzuki⁴, Takao Fukuoka^{5,6}, ¹Toyo University, ²Aichi Gakuin University, ³Kyoto University, ⁴Archylis / Japan FB3-2 Silver-Based Metal-Organic Decomposition with 3D Inkjet Printing for Selective Package-level EMI Shielding M. H. Chen, W. H. Wang, R. J. Kao, Y. E. Yeh, Advanced Semiconductor Engineering / Taiwan FB3-3 Inducing Dynamic Percolation of Stretchable Printed Wires During Three-dimensional Forming Rina Aida, Masahiro Inoue, Gunma University / Japan FB3-4 Fine Printing by Gravure Offset Using Lowtemperature Sintered Copper Shingo Ohshima, Chisato Oyama, Yoshihiro Ohyama, Ikeda Hideki, KOMORI / Japan</p>	<p>FC3: Advanced Packaging-7 Chairs: Kiyokazu Yasuda, The University of Osaka, Junsha Wang, Meisei University FC3-1 <Session Invited> PLP Market Trend Yik Yee Tan, Yole Group / France FC3-2 Next Generation Chiplet Technology Development: Focusing on Fine RDL Patterning M. Sasago^{1,6}, H. Nishizawa^{2,6}, T. Doi^{3,6}, M. Ozono⁴, H. Kimuro⁵, S. Yamamoto^{3,4}, K. Suzuki³, S. Takahashi², Y. Minami^{1,6}, M. Yasuda^{1,2}, Y. Hirai^{1,2}, T. Saito^{1,2}, ¹Osaka Metropolitan University (OMU), ²Doi Laboratory, ³National Institute of Advanced Industrial Science and Technology (AIST), ⁴Kyushu Institute of Technology, ⁵Lihtotech Japan, ⁶RCS consortium / Japan FC3-3 Investigation from the Lithography of the Possible of Forming Less Than 8 μm Pitch Required for Advanced Packaging Yu Abe, Naoya Sohara, Ryotaro Takahashi, Toshimitsu Arai, Hirotsuke Takamatsu, USHIO / Japan FC3-4 Advanced Post Overlay Compensation for Enhanced Lithography Overlay Accuracy for Next-Generation AICS Packaging John Chang, Keith Best, Xin Song, Timothy Chang, Onto Innovation / US</p>	<p>FD3: Thermal Management-2 Chairs: Chuantong Chen, The University of Osaka, Hitoshi Sakamoto, Huawei Technologies Japan FD3-1 <Session Invited> Two-Phase In-Situ Thin Liquid Film Cooling for Computing Module with 600W/cm² Heat Flux Qidong Wang, IMECAS / China FD3-2 Improvement of Air-Cooling Performance Utilizing Breathing Phenomenon Induced by Corrugated Lotus Copper Fins R. Kubota¹, K. Yuki¹, K. Yuki¹, T. Ogushi², M. Murakami², T. Ide², ¹Tokyo University of Science, ²Lotus Thermal Solution / Japan FD3-3 Cu/Diamond Composite Heat Spreader for Thermal Management of Advanced Electronic Devices Masato Sakai, Satoshi Teraji, Tasuku Hamano, Ishihara Chemical / Japan</p>	<p>FE3: Materials for High Speed Application Chairs: Yoji Nakajima, TOKYO ELECTRON, Ying Ying Lim, AIST FE3-1 <Session Invited> Thin-Film Lithium Niobate Based High-Speed Modulator and Future Perspective Rai Kou¹, Toshiya Murai¹, Kazumasa Takabayashi², Masahiko Imai¹, Guangwei Cong¹, Koji Yamada¹, ¹AIST, ²Fujitsu Optical Components / Japan FE3-2 High-Speed Signal Transmission Rigid Substrate Fabricated by Silver-Seed Semi Additive Process Rei Tamura, Akira Murakawa, Norimasa Fukazawa, Wataru Fujikawa, DIC / Japan FE3-3 Material Property Extraction Using Microstrip Antennas for mm-Wave Applications Tian-Lin Zhanz, Sung-Mao Wu, Bo-Yang Jheng, Guan-Yu Hong, National University of Kaohsiung / Taiwan</p>
16:10	<p align="center">Break</p>				
16:10-16:30	<p align="center">Break</p>				

	Room A	Room B	Room C	Room D	Room E
16:30	FA4: Automation Technology for Wafer/Panel Level Process Chair: Yasuhiro Morikawa, ULVAC FA4-1 <Session Invited> Reimaging and Transforming Package Assembly and Test Manufacturing Jeffrey S Pettinato ^{1,2} , Intel / US, ³ SATAS / Japan FA4-2 <Session Invited> Automated Material Handling System (AMHS) as Blood Vessels in a Semiconductor Factory Kenji Kumagai, Wataru Kitamura, Murata Machinery / Japan FA4-3 <Session Invited> Automation Technology for Wafer/Panel Level Process Shinichi Nakashima, DAIFUKU / Japan FA4-4 <Session Invited> Automated Material Handling System Mitsunori Harada, SHARP / Japan FA4-5 <Session Invited> Automatic Transportation AMR (Autonomous Mobile Robot) System For Advanced Back-end Processes Kazuma Nakaguchi, SINFONIA TECHNOLOGY / Japan	FB4: Adv. Cu Interconnect Technologies for Chiplets Chairs: Fumihiro Inoue, YOKOHAMA National University, Yoji Nakajima, TOKYO ELECTRON FB4-1 <Session Invited> Chip-let Heterogeneous Integration Packaging Based on Fan-Out Interposer Technology Jung Won Lee, nepes / Korea FB4-2 <Session Invited> Advanced Substrate for High Performance AI Computing System Yu-Hua Chen, Unimicron / Taiwan FB4-3 <Session Invited> Integrated Systems Approach from an Equipment Supplier's Perspective in the Advanced Packaging Era Hiroataka Satori, Ji Chul Yang, EBARA / Japan FB4-4 <Session Invited> High-Resolution Direct-Write System for Advanced Package by Unique Spatial Light Modulator Yuichi Nishimoto, SCREEN Holdings / Japan	FC4: Advanced Packaging-8 Chairs: Noriyuki Fujimori, OLYMPUS, Shoji Uegaki, Crane Research FC4-1 Reliability and Warpage of High Density Package Using Organic Interposer for Heterogeneous Integration Yoshihiro Kobayashi, Shota Miki, Shinko Electric Industries / Japan FC4-2 RDL Formation Using Low Df Thermosetting Film (Progress of the Chiplet Integration Platform Consortium in Japan) Yusuke Naka ¹ , Meiten Koh ¹ , Ichiro Kono ² , Yasuhiro Morikawa ³ , Takafumi Fukushima ⁴ , Yoichiro Kurita ⁵ , Taiyo Ink MFG, ⁶ AOI Electronics, ⁷ ULVAC, ⁸ Tohoku University, ⁹ Institute of Science Tokyo / Japan FC4-3 Surface Modification for PI-to-PI Direct Bonding Yu-Kuang Chen, Chang-Ju Hsu, Jenn-Ming Song, National Chung Hsing University / Taiwan FC4-4 Advancements in IC Substrate Packaging: A Process to Metallize Embedded Trench for Enhanced Performance and Sustainability Saminda Dharmarathna ¹ , Fengqi Zhang ¹ , Maddux Sy ² , Howard Chu ³ , Leslie Kim ⁴ , Brian Gokey ⁵ , Ernie Long ⁶ , ⁷ MacDermidAlpha Electronics Solutions / US ⁸ MacDermidAlpha Electronics Solutions / Taiwan	FD4: Thermal Management-3 Chairs: Go Hamasaka, Tokuyama, Tomoyuki Hatakeyama, Toyama Prefectural University FD4-1 <Session Invited> Thermal Test Vehicles for Characterization of the Thermal Performance for Large Silicon Chips Dongkai Shangquan, Thermal Engineering Associates / US FD4-2 Power Devices Sandwiched Between Silver-Diamond Parts for High Performance Module R. Khazaka ¹ , A. Casado Ramoneda ^{1,2} , Y. Avenas ³ , T. Youssef ⁴ , C. Gautier ⁵ , S. Azzopardi ⁶ , T. Murakami ⁷ , M. Tamaru ⁸ , Safran SA, ⁹ Univ. Grenoble Alpes / France, ¹⁰ TECNISCO / Japan FD4-3 Thermal Transfer Analysis by Phonon Vibrations at Interface Between Filler and Resin in Thermal Interface Material Osamu Arao, Masashi Kitsuenezuka, Akira Shintai, DENSO / Japan FD4-4 Verification of Differences in Thermal Resistance of Cascade Device Packages Due to Heating Power Ratio of Heat Sources Aiko Shimada, Wasanthamala Badalawa, Yoshitaka Aoki, Tomoaki Hara, Siemens / Japan	
18:10					

Poster Session

Poster sessions will be held from 15:40-16:40 on April 16 and from 17:40-18:40 on April 17.

P01	Optimization of PVD SiCN Deposition for Cu/SiCN Hybrid Bonding Applications Junyoung Choi, Sun Jang, Dongmyeong Lee, Hoogwan Lee, Sarah Eunkyung Kim, Seoul National University of Science and Technology / Korea	P12	Within-Wafer and Within-Die Uniformity of Bond Strength for Hybrid Bonding Daiki Kobayashi ¹ , Junya Fuse ¹ , Yusuke Kondo ² , Yuki Yoshihara ³ , Marie Sano ⁴ , Fumihiro Inoue ¹ , Yokohama National University, ² Kanagawa Institute of Industrial Science and Technology (KISTEC) / Japan	P24	Cancelled	P35	Preparation of UCr ₂ C ₂ -type Fluorescent Fiber (Na ₂ ·K ₂ Li ₂ ·Li ₂ SiO ₄) ₂ ·zEu ²⁺ By to change the ratio of K and Li by Electrospinning J. Y. Shih, Y. J. ZHU, C. L. Chung, J. D. Lin, I-SHOU University / Taiwan
P02	Exploring the Potential of Fly Cutting for Polymer Planarization in Cu/PDMS Hybrid Bonding Sun Jang, Junyoung Choi, Dongmyeong Lee, Hoogwan Lee, Sarah Eunkyung Kim, Seoul National University of Science and Technology / Korea	P13	Implementation of Double-Side Calibration and Measurement for Q-Band 50GHz Application Chia-Chu Lai, Sam Lin, Vito Lin, Andrew Kang, Yu-Po Wang, Siliconware Precision Industries / Taiwan	P25	A Mild Surface Activation Using Vacuum Ultraviolet Irradiation under Redox Gases for Semiconductor Bonding Materials S. Endo ¹ , A. Shimizu ^{2,3} , Ushio, ⁴ Gifu University / Japan	P36	Mechanical Properties Characterization of Silicon Carbide Coated Graphite Composites for MOCVD Structural Design Kuo-Shen Chen, Hsuan-Ting Huang, Wu-Jun Liu, Tzu-En Liu, Yi-Hsuan Wei, Ching-Jenq Ho, National Cheng-Kung University / Taiwan
P03	Effect of Noble Metal Passivation Deposited by ECD on Cu Surface for Low-Temperature Cu-to-Cu Bonding Dongmyeong Lee, Junyoung Choi, Sun Jang, Hoogwan Lee, Sarah Eunkyung Kim, Seoul National University of Science and Technology / Korea	P14	The Application of Electric Feed-in with the Low Sensitivity and Low Spatial Resolution Probe Yu-Kai Kuo, Guan-Yu Hong, Tsai-Feng Wu, Shin-Shian Wu, Yu-Zhi Ma, Sung-Mao Wu, National University of Kaohsiung / Taiwan	P26	Optimization of Au-Ag-Pd Alloy Wire Bonding for Stacked NAND Flash Min-Cheng Huang ¹ , Ruenn-Bo Tsai ¹ , Jin-Bao Wang ² , Chao-Yung Wang ³ , Tsung-Jen Kang ⁴ , National Sun Yat-sen University, ⁵ Orient Semiconductor Electronics / Taiwan	P37	Interfacial Reactions in Sn/Ag/Cu Sandwiched Structure Yu-Xuan Yang, Chih-Ming Chen, National Chung Hsing University / Taiwan
P04	Advanced Package Solution Applied on High Performance Computing for Heterogeneous Integration Chen Chao Wang, Chih Yi Huang, Hung Chun Kuo, Ming Fong Zhong, Fu Chen Chu, Chung Hung Lai, Hung Hsien Huang, Lee Hsu Yang, Chih Pin Hung, CRD ASE / Taiwan	P15	Efforts to Improve the Accuracy of Simulation Technology for Package Substrates by Acquiring Realistic Material Properties Satoshi Nakamura, Aki Tanaka, Kyocera / Japan	P27	Development Fine Pitch Organic Hybrid Bonding Application Chih-Jing Hsu ¹ , Che-Ming Hsu ¹ , Min-Tzu Hsu ¹ , Hsu-Nan Fang ² , Yuan-Feng Chiang ³ , Jen-Chieh Kao ⁴ , Yung-I Yeh ⁵ , Kazuaki Ebisawa ⁶ , Makiko Irie ⁷ , ⁸ Advanced Semiconductor Engineering (ASE) Group / Taiwan, ⁹ Tokyo Ohka Kogyo / Japan	P38	Development of Indium-Based Low Temperature Solder Alloys for Martian Conditions Jiye Zhou ¹ , Xin F. Tan ² , Stuart D. McDonald ³ , Tetsuro Nishimura ⁴ , Kazuhiro Nogita ⁵ , The University of Queensland / Australia ⁶ Nihon Superior / Japan
P05	Study of Low Temperature Cu-to-Cu Bonding using Reducing Plasma Hoogwan Lee, Dongmyeong Lee, Junyoung Choi, Sun Jang, Sarah Eunkyung Kim, Seoul National University of Science and Technology / Korea	P16	Monopole and Loop Feed-in Substrate Integrated Waveguide Splitter Design Yi-Chang Tsai, Sung-Mao Wu, National University of Kaohsiung / Taiwan	P28	A Transceiver IC Development for Wired Data Communication Using Mode Division Multiplex Transmission Method Ryoma Sakida ¹ , Hayato Yatabe ² , Yuki Fukumoto ³ , Tohru Matsushima ⁴ , Takefumi Yoshikawa ⁵ , Toyama Prefectural University, ⁶ Kyushu Institute of Technology / Japan	P39	Basic Investigation to Simplify the Prototype of Fat-Equivalent Electromagnetic Phantom for Microwave Mammography Kotomi Inada, Takahiko Yamamoto, Tokyo University of Science / Japan
P06	Low-Temperature Femtosecond Laser Processing for Enhanced Via Hole Morphology in Semiconductor Packaging Taesik Kim ^{1,2} , Jaebom Lee ² , Seon-Jin Choi ³ , Jiyong Park ^{3,4} , ⁵ Korea Institute of Industrial Technology (KITECH), ⁶ Hanyang University, ⁷ Korea National University of Science and Technology (UST) / Korea	P17	Design and Experimental Verification of Electric Near Field Probe Bing-Wei Chen, Sung-Mao Wu, National University of Kaohsiung / Taiwan	P29	The Post Mold Cure Effect on the Microstructural and Mechanical Properties of Ag and Cu Joints ByeongChan Kim ¹ , Yehri Kim ² , Dongjin Kim ³ , ⁴ Korea Institute of Industrial Technology (KITECH), ⁵ Korea University / Korea	P40	Effects of Current Mode and Electrodes on the Properties of Electroplated Fe-Ni Invar Alloy N.Y. Kang, J. H. Lee, Hongik University / Korea
P07	Signal Integrity Enhancement of Die-to-Die Interconnection by Using a Vertically Asymmetric Pattern Jaewon Lee ^{1,2} , Kihun Ok ¹ , SoYoung Kim ¹ , ² Sungkyunkwan University, ³ Samsung Electronics / Korea	P18	Blue Microfluidic Electrogenerated Chemiluminescence Cell Using a Fluorescent Emitter and a Redox Mediator Ayari Tabori ¹ , Sara Yamaguchi ¹ , Ryoichi Ishimatsu ² , Takashi Kasahara ³ , ⁴ Hosei University, ⁵ University of Fukui / Japan	P30	Application of Indium Sheet Thermal Interface Material in Advanced Semiconductor Packaging Wen-Yu Teng ¹ , Leon Li ¹ , Debby Li ¹ , Terry Hou ¹ , Liang Yih Hung ² , Andrew Kang ³ , Don Son, Jiang ⁴ , Yu-Po Wang ⁵ , Lewis Huang ⁶ , ⁷ Siliconware Precision Industries, ⁸ Senju Metal Industry / Taiwan	P41	Surface Treatment of AIN Filler for Improvement of Reliability in Silicone Resin Composites M. Takakusaki, I. Masada, Y. Iizuka, T. Hamasaka, A. Sakamoto, G. Hamasaka, Tokuyama / Japan
P08	Simulation of Signal Integration and Power Integration in Advanced Packaging Circuit Design Shu-Chin Huang, Sung-Mao Wu, National University of Kaohsiung / Taiwan	P19	Adhesion of Si and LiNbO ₃ via Perhydrodopolysilazane for Photonic Substrate Fabrication Kei Hishinuma, Kai Takeuchi, Eiji Higurashi, Tohoku University / Japan	P31	Preparation of Fluorine-Free, Transparent, Hydrophobic Coatings as Protectors for Electronic Packaging Chih-Feng Wang ¹ , Meng-Hang Tsai ¹ , Sheng-Hsiang Hsu ² , ³ National Sun Yat-sen University, ⁴ Advanced Semiconductor Engineering / Taiwan	P42	Estimation of Adhesive Strength and Thermal Cycling Lifetime with MD Simulation and FEA for Die-Attach Sintering Paste (Cu, Ag) Dai Ishikawa ¹ , Hideo Nakako ¹ , Thomas Blank ² , Felix Steiner ³ , ⁴ Resonac / Japan, ⁵ Karlsruhe Institute of Technology / Germany
P09	Analysis of Parasitic Effects in Packaging with RDL Jyun-yu Chen, Sung-Mao Wu, Shin-Shian Wu, National University of Kaohsiung / Taiwan	P20	Indium Through Si Via for Quantum Chiplet Integration Yugi Otake, Mai Thi Ngoc La, Kenta Hayama, Jowsh Avisheik Gounder, Fumihiro Inoue, Yokohama National University / Japan	P32	Evaluation of the Oxidation Resistance of Cross-linked Gelatin-Coated Copper Particles Tatsuya Yamaguchi, Hiroki Tsukamoto, Tetsu Yonezawa, Hokkaido University / Japan	P43	Silver Paste Transferability During Imprinting Using PDMS Replica Mold H. Komatsu, D. Sakai, N. Shimoishizaka, CONNECTEC JAPAN / Japan
P10	Parametric Investigation of Surface Morphology in Through Glass Vias (TGVs) Fabricated via Femtosecond Laser Processing Jaebom Lee ^{1,2} , Taesik Kim ² , Seung Hwan Lee ³ , Jiyong Park ^{3,4} , ⁵ Korea Institute of Industrial Technology (KITECH), ⁶ Hanyang University, ⁷ Korea National University of Science and Technology (UST) / Korea	P21	High-Precision Thin-Film Bending Sensor with Fully Sliding Packaging Structure for Robotic Surgical Endoscope Hao Liu ¹ , Michitaka Yamamoto ¹ , Toshihiro Itoh ¹ , Seiichi Takamatsu ¹ , ² The University of Tokyo / Japan, ³ State University of New York / US	P33	Characterization of Chitin or Chitosan/PCL Nanofibers Prepared by Electrospinning K. H. WU, C. Y. WU, C. L. CHUNG, I-SHOU University / Taiwan	P44	Solid-State Mg Heat Sink Direct Cooling Bonding with Refill Friction Stir Spot Bonding for Power Inverters Sihun Park ^{1,2} , Shin-II Kim ¹ , Yehri Kim ^{1,2} , Seungyeop Baek ³ , Dongjin Kim ⁴ , ⁵ Korea Institute of Industrial Technology (KITECH), ⁶ Korea University, ⁷ Korea Automotive Technology Institute (KATECH) / Korea
P11	Cu Metallized Glass Core Evaluation & Testing Method T. Onishi ^{1,2} , A. Okimoto ¹ , K. Inoue ¹ , T. Watanabe ¹ , M. Takayama ¹ , ² Koto Electric / Japan ³ Grand Joint Technology / Hong Kong	P22	High-Speed Signal Transmission Comparative Analysis of Huray and Grosse Models for Copper Foil Surface Roughness Yu-Zhi Ma, Shin-Shian Wu, Sung-Mao Wu, Tsai-Feng Wu, Yen-Ting Lu, National University of Kaohsiung / Taiwan	P34	PFAS-Free Assembly Material Development Wei-Chun Chen, Han-Gung Chen, Fenny Liu, Liang-Yih Hung, Andrew Kang, Yu-Po Wang, Siliconware Precision Industries / Taiwan	P45	Research on System Circuit Electrothermal Analysis Based on Non-Contact Near-Field Measurement Cheng Hsuan Liu ^{1,2} , Sung Mao Wu ^{1,2} , ³ Micro Electronic Packaging Laboratory, ⁴ National University of Kaohsiung / Taiwan